

# Fieldbus Power Hub, Power Supply Module

#### HD2-FBPS-1.25.360

- 2 segments, simplex, individual modules per segment
- Couples PROFIBUS PA devices transparently to PROFIBUS DP
- High-power trunk: Live work on devices in any hazardous area
- Transparent, configuration free
- Optimized for size and quality, low heat dissipation
- Automatically adapts speed on DP up to 12 Mbit/s
- Output: 25 ... 28 V/360 mA
- Universal power supply for most applications
- With galvanic isolation
- Installation in Zone 2/Class I, Div. 2
- For FOUNDATION Fieldbus H1 and PROFIBUS PA
- High efficiency, low heat dissipation for high packing density
- Hot swappable in redundant configuration
- Module exchange without tools during operation

2-channel power supply system, modular, motherboard-based with transparent coupling between PROFIBUS DP and PA. motherboard and modules











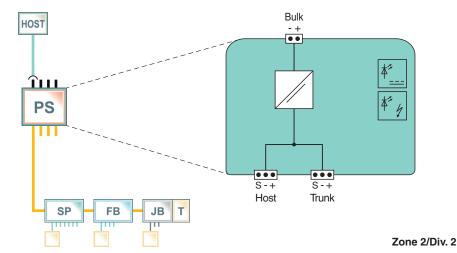
#### **Function**

This Power Supply Module is a system component for the FieldConnex® Power Hub and can be plugged into the motherboard. It adapts current and voltage for the supply of fieldbus segments and field devices.

This power supply satisfies the needs of most fieldbus applications with regards to cable lengths and number of devices.

Reliability of communication is enhanced through galvanic isolation between segment and bulk power supply. Two LEDs indicate power and status. In redundant configuration two modules are connected in parallel via simple circuits ensuring seamless operation.

### Connection



#### **Technical Data**

Release date: 2023-12-19 Date of issue: 2023-12-19 Filename: 189516\_eng.pdf

General specifications		
Design / Mounting		Motherboard based
Supply		
Rated voltage	$U_{r}$	19.2 35 V DC
Rated current	l <sub>r</sub>	670 360 mA
Power dissipation		typ. 2 W



#### Technical Data Fieldbus connection $U_N$ 25 ... 28 V Rated voltage Rated current $I_N$ 360 ... 10 mA Short-circuit current typ. 400 mA Indicators/operating means LED ERR red flashing: overload error at output LED PWR Power LED: green if Uout > 25 V **Galvanic isolation** Fieldbus segment/Supply functional insulation acc. to IEC 62103, rated insulation voltage 250 Veff **Directive conformity** Electromagnetic compatibility Directive 2014/30/EU EN 61326-1:2013 Standard conformity Electromagnetic compatibility NE 21:2011 Degree of protection IEC 60529 IEC 61158-2 Fieldbus standard EN 60068-2-27 Shock resistance Vibration resistance EN 60068-2-6 Corrosion resistance acc. to ISA-S71.04-1985, severity level G3 **Ambient conditions** Ambient temperature -40 ... 60 °C (-40 ... 140 °F) Storage temperature -40 ... 85 °C (-40 ... 185 °F) Relative humidity < 95 % non-condensing Shock resistance 15 g 11 ms Vibration resistance 1 g , 10 ... 150 Hz Corrosion resistance acc. to ISA-S71.04-1985, severity level G3 Mechanical specifications Connection type motherboard specific Core cross section motherboard specific Housing material Polycarbonate Housing width 18 mm 106 mm Housing height Housing depth 128 mm Degree of protection IP20 Mass approx. 150 g Mounting motherboard mounting Data for application in connection with hazardous areas Certificate TÜV 06 ATEX 553229 X Marking Directive conformity Directive 2014/34/EU EN 60079-0:2012, EN 60079-11:2012, EN 60079-15:2010 International approvals FM approval FM certificate FM 19 US 0015 X and FM 19 CA 0011 X FM marking AEx/Ex ec IIC T4 IECEx approval IECEx TUN 11.0003X IECEx certificate IECEx marking Ex nA IIC T4 Gc

Refer to "General Notes Relating to Pepperl+Fuchs Product Information"

Certificates and approvals

Supplementary information

Marine approval

**General information** 

DNV A-14038

where applicable. For information see www.pepperl-fuchs.com.

Observe the certificates, declarations of conformity, instruction manuals, and manuals

## **Assembly**



